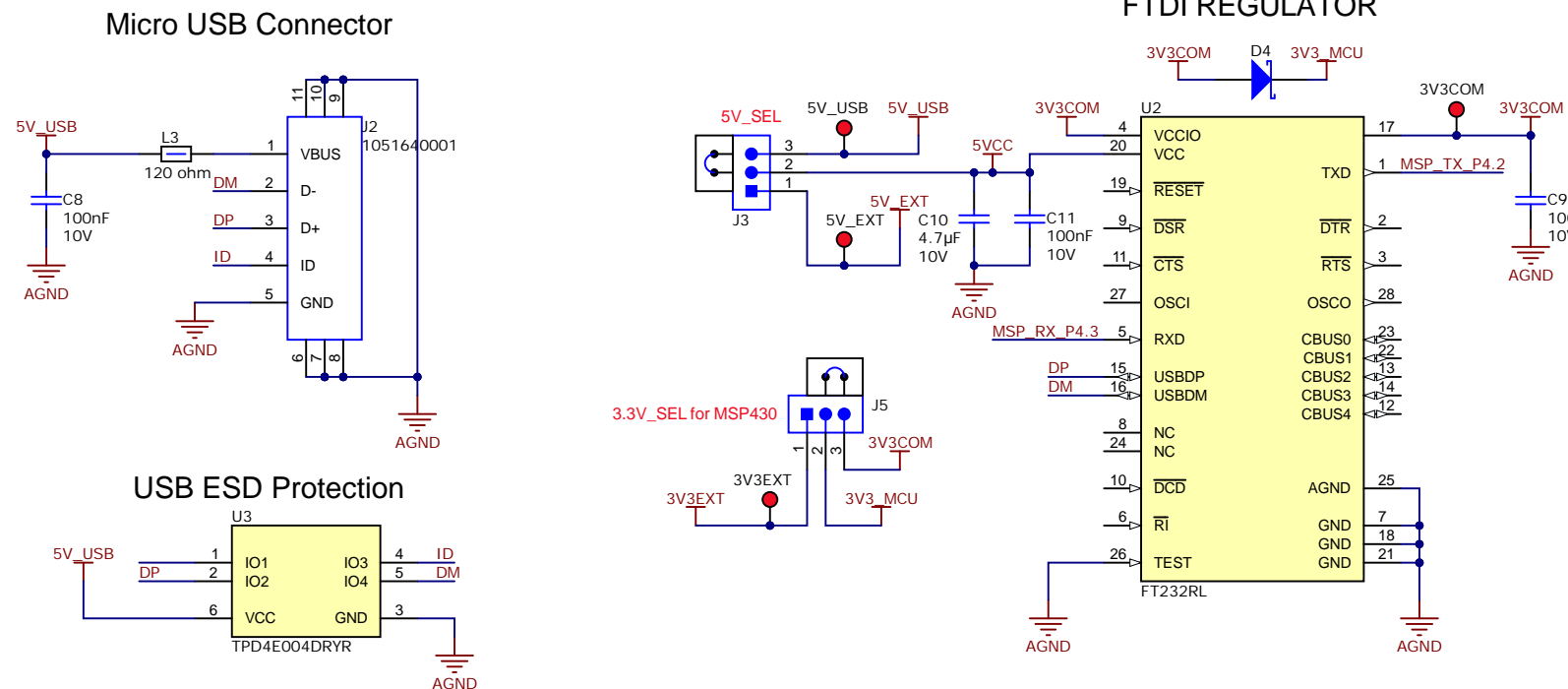
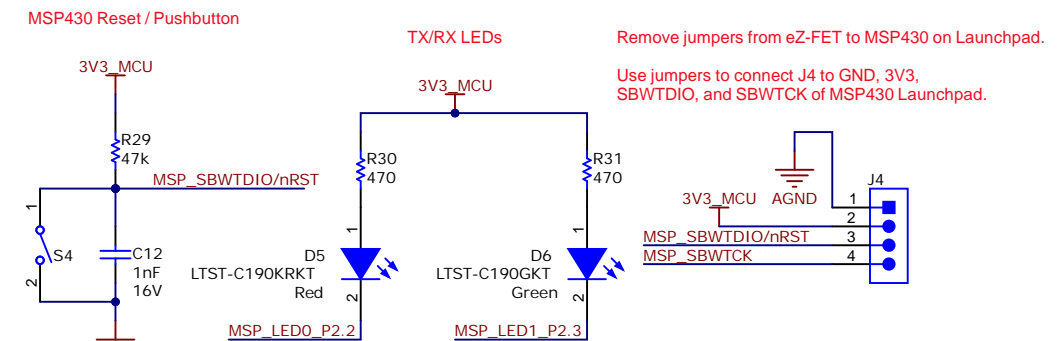


FTDI

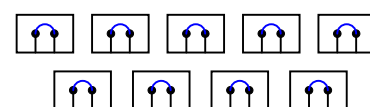
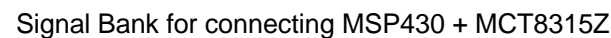


MCU PROGRAMMING



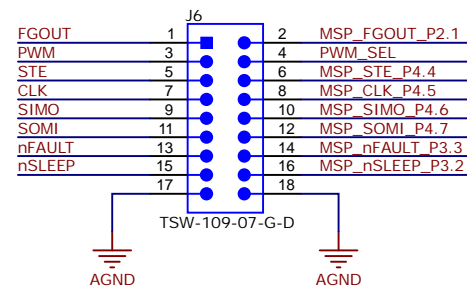
MSP430FR2355IPT

MSP430FR2355

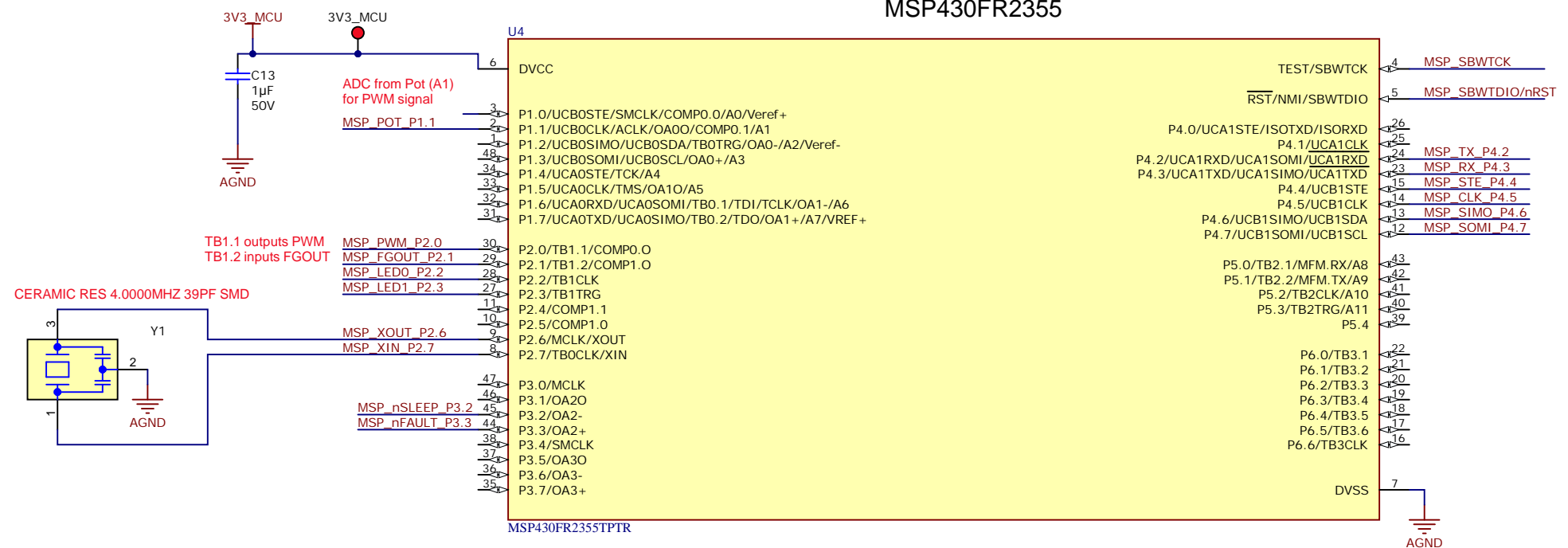


To MCT8315Z

To MSP430FR2355 (except PWM_SEL)



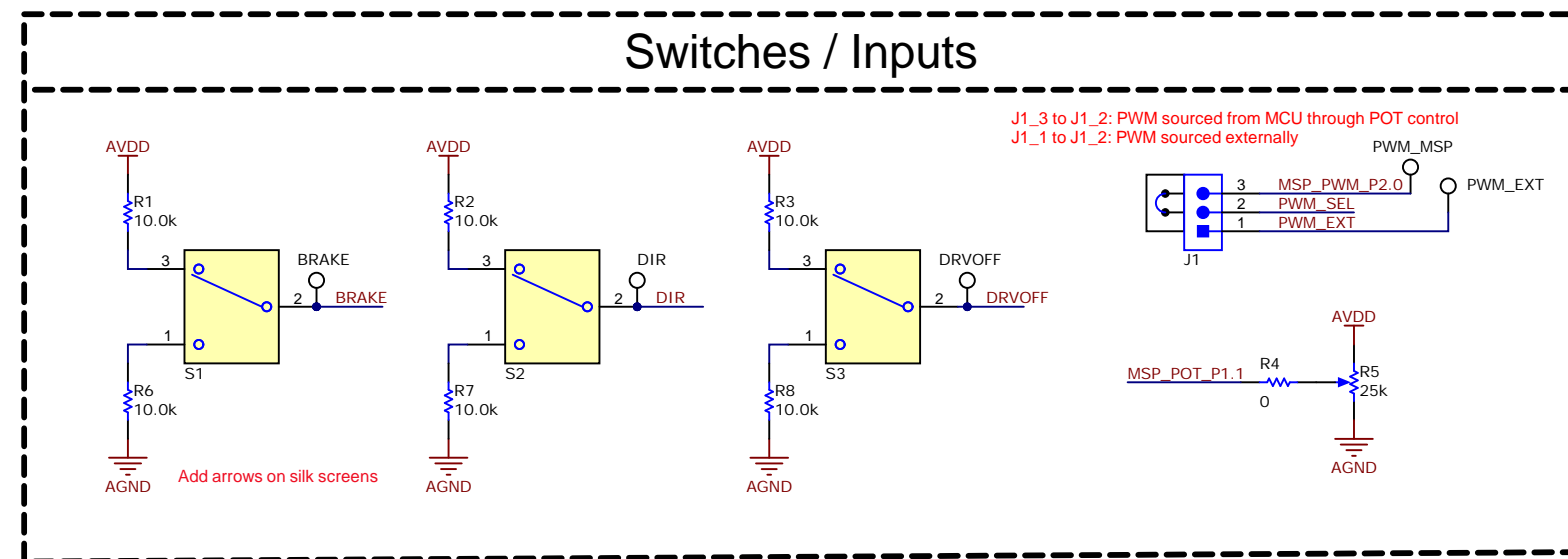
Populate jumpers to communicate onboard MSP430FR2355 to the MCT8315Z or depopulate jumpers to use standalone MSP430 or MCT8315Z.




Orderable:	MCT8315ZVM	Designed for:	Public Release	Mod. Date:	9/8/2023
TID #:	N/A	Project Title:	MCT8315ZVM		
Number:	MD079	Rev:	A	Sheet Title:	
SVN Rev:	Not in version control		Assembly Variant:	003	Sheet: 1 of 5
Drawn By:			File:	MD079_INTERFACE.SchDoc	Size: B
Engineer:	Hong Ze Khor		Contact:	http://www.ti.com/support	



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Orderable: MCT8315ZEV	Designed for: Public Release	Mod. Date: 8/22/2023	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2023
TID #: N/A	Project Title: MCT8315ZEV		
Number: MD079	Rev: A	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 003	Sheet: 2 of 5	
Drawn By:	File: MD079_CONTROL_SchDoc	Size: B	
Engineer: Hong Ze Khor	Contact: http://www.ti.com/support		

A

B

C

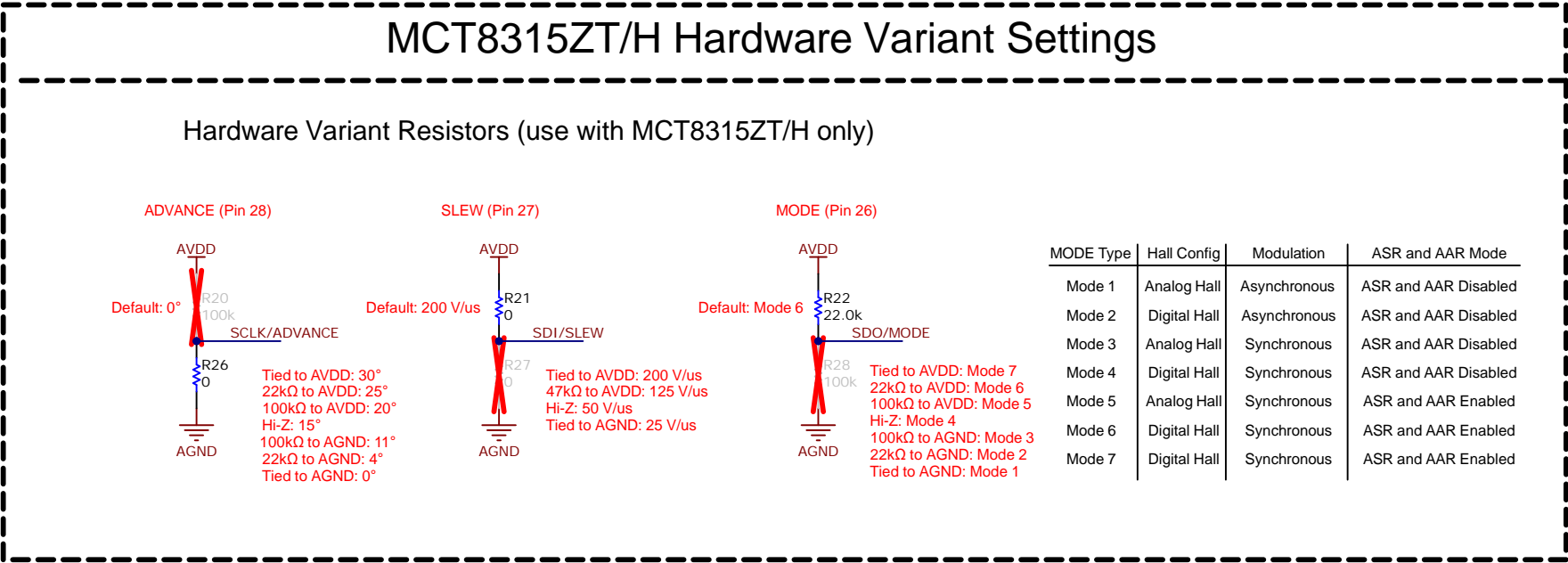
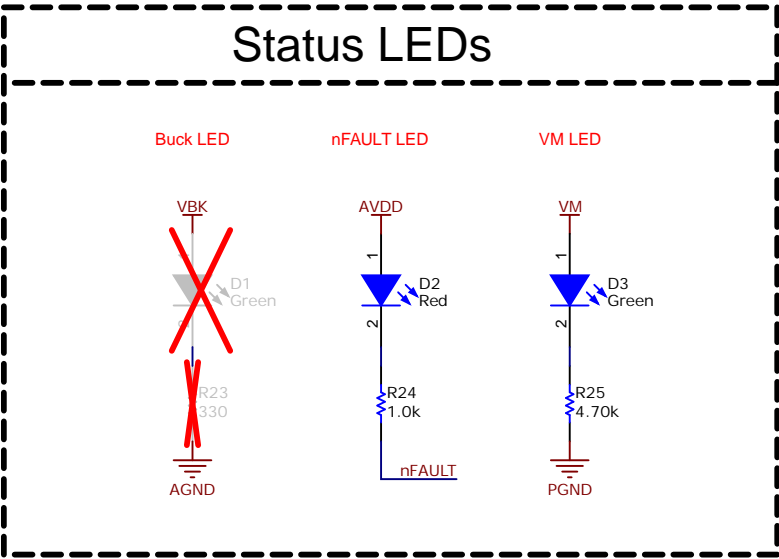
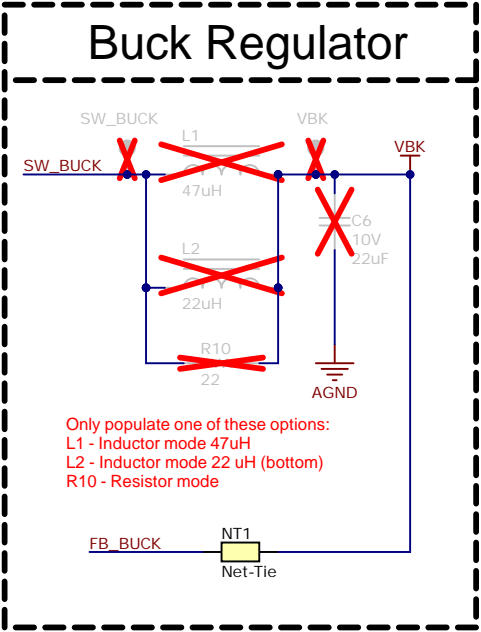
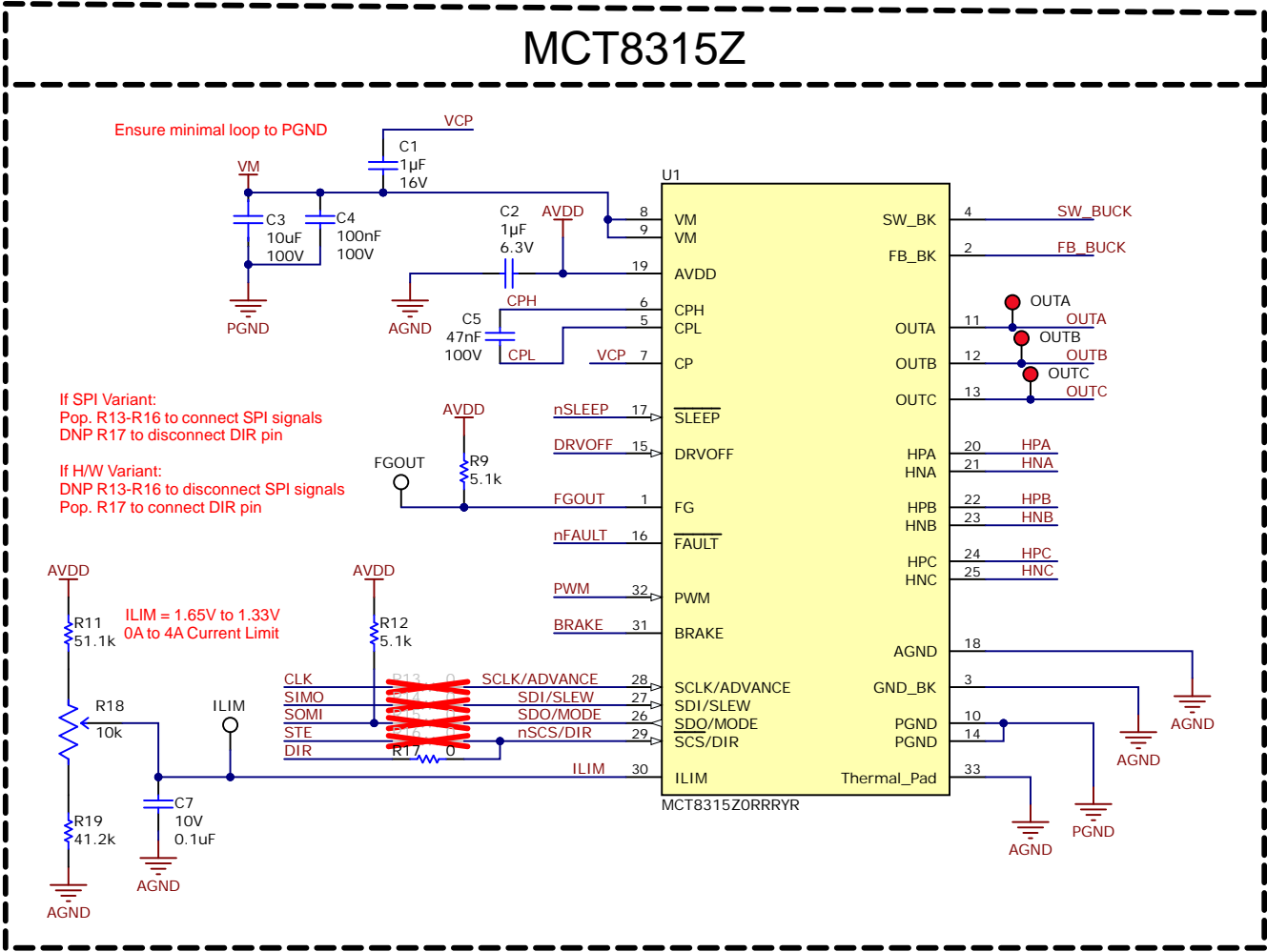
D

A

B

C

D

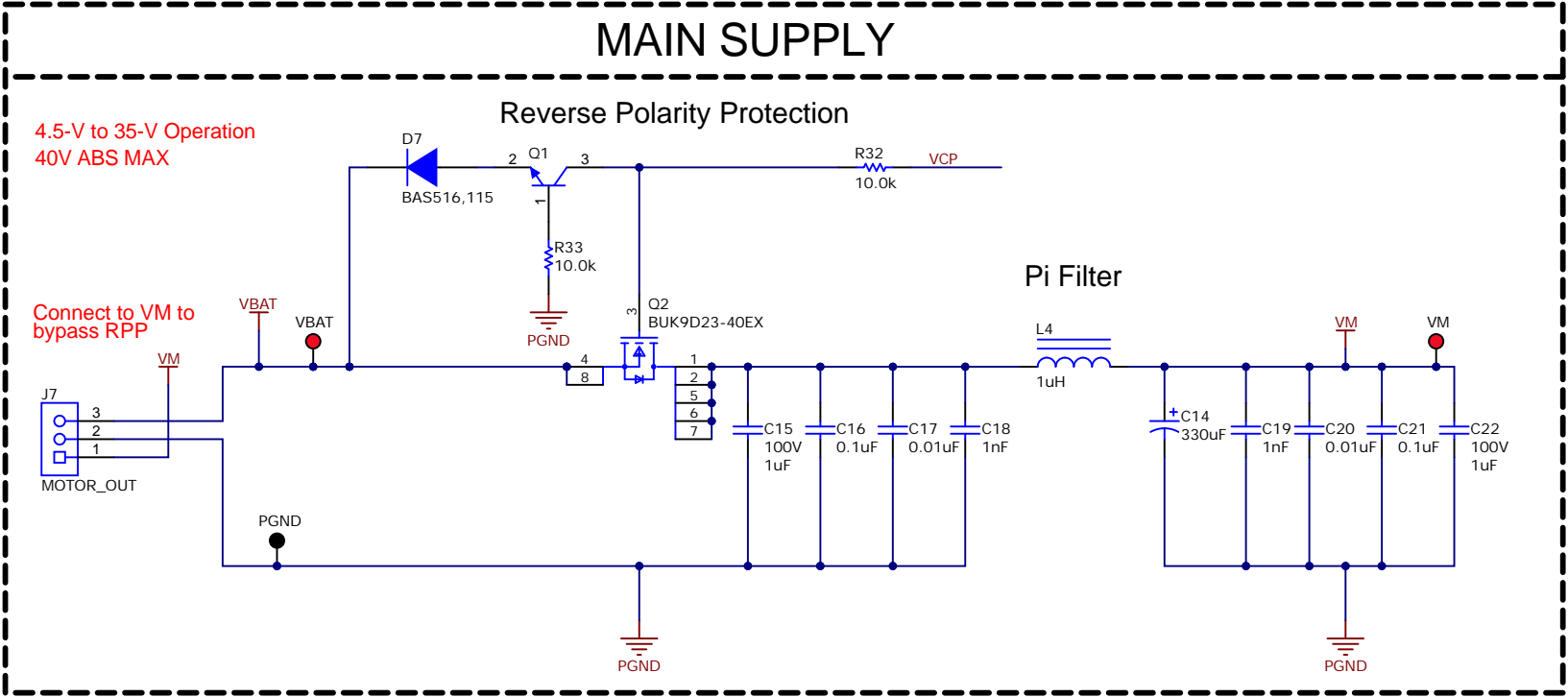


A

B

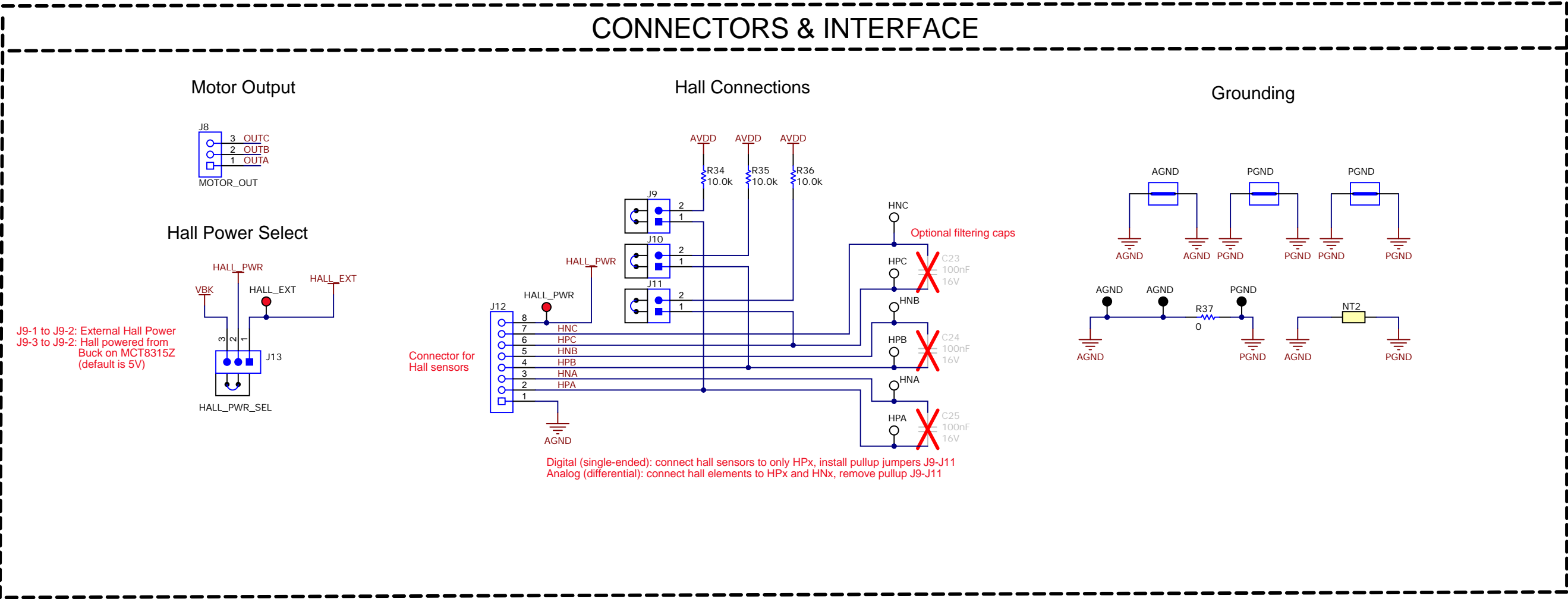
A

B



C

C

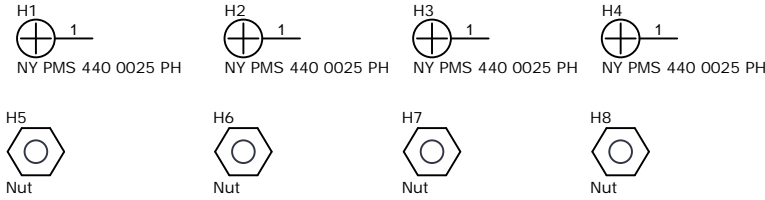


D

D

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Orderable: MCT8315ZEVM	Designed for: Public Release	Mod. Date: 8/22/2023
TID #: N/A	Project Title: MCT8315ZEVM	
Number: MD079	Rev: A	Sheet: 4 of 5
SVN Rev: Not in version control	Assembly Variant: 003	File: MD079_POWER_AND_CONNECTORS.SchDoc
Drawn By: Hong Ze Khor	Contact: http://www.ti.com/support	



PCB Number: MD079
PCB Rev: A

PCB
LOGO
Texas Instruments



PCB
LOGO
FCC disclaimer

PCB
LOGO
WEEE logo

LBL1
PCB Label
THT-14-423-10



CAUTION HOT SURFACE



CAUTION HOT SURFACE

Variant/Label Table	
Variant	Label Text
001	MCT8315ZEVMSPI
002	MCT8315ZEVMSHW
003	MCT8315ZEVMSHW, NO BUCK

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.